

74ALVT16823

18-bit bus-interface D-type flip-flop with reset and enable;
3-state

Rev. 5 — 22 January 2018

Product data sheet

1 General description

The 74ALVT16823 18-bit bus interface register is designed to eliminate the extra packages required to buffer existing registers and provide extra data width for wider data/address paths of buses carrying parity.

The 74ALVT16823 has two 9-bit wide buffered registers with clock enable (pin \overline{nCE}) and master reset (pin \overline{nMR}) which are ideal for parity bus interfacing in high microprogrammed systems.

The registers are fully edge-triggered. The state of each D input, one set-up time before the LOW-to-HIGH clock transition is transferred to the corresponding Q output of the flip-flop.

It is designed for V_{CC} operation from 2.5 V to 3.0 V with I/O compatibility to 5 V.

2 Features and benefits

- Two sets of high speed parallel registers with positive edge-triggered D-type flip-flops
- 5 V I/O compatible
- Ideal where high speed, light loading, or increased fan-in are required with MOS microprocessors
- Bus hold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion and extraction permitted
- Power-up 3-state
- Power-up reset
- No bus current loading when output is tied to 5 V bus
- Output capability: +64 mA to -32 mA
- Latch-up protection:
 - JESD78: exceeds 500 mA
- ESD protection:
 - MIL STD 883, method 3 015: exceeds 2000 V
 - MM: exceeds 200 V

3 Ordering information

Table 1. Ordering information

Type number	Package			Version
	Temperature range	Name	Description	
74ALVT16823DL	-40 °C to +85 °C	SSOP56	plastic shrink small outline package; 56 leads; body width 7.5 mm	SOT371-1
74ALVT16823DGG	-40 °C to +85 °C	TSSOP56	plastic thin shrink small outline package; 56 leads; body width 6.1 mm	SOT364-1

4 Functional diagram

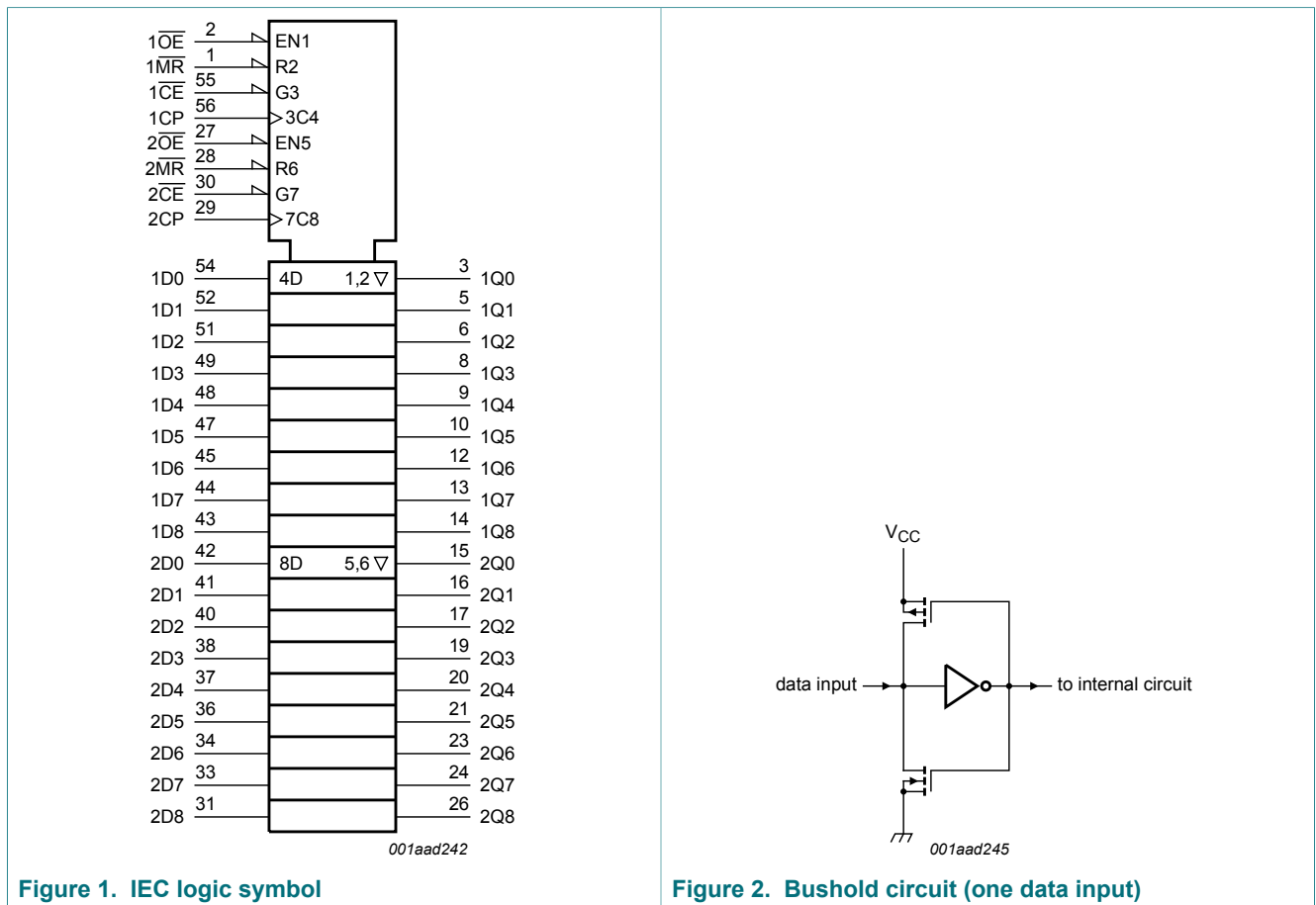


Figure 1. IEC logic symbol

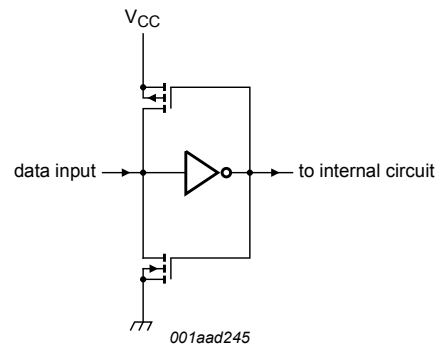


Figure 2. Bushold circuit (one data input)

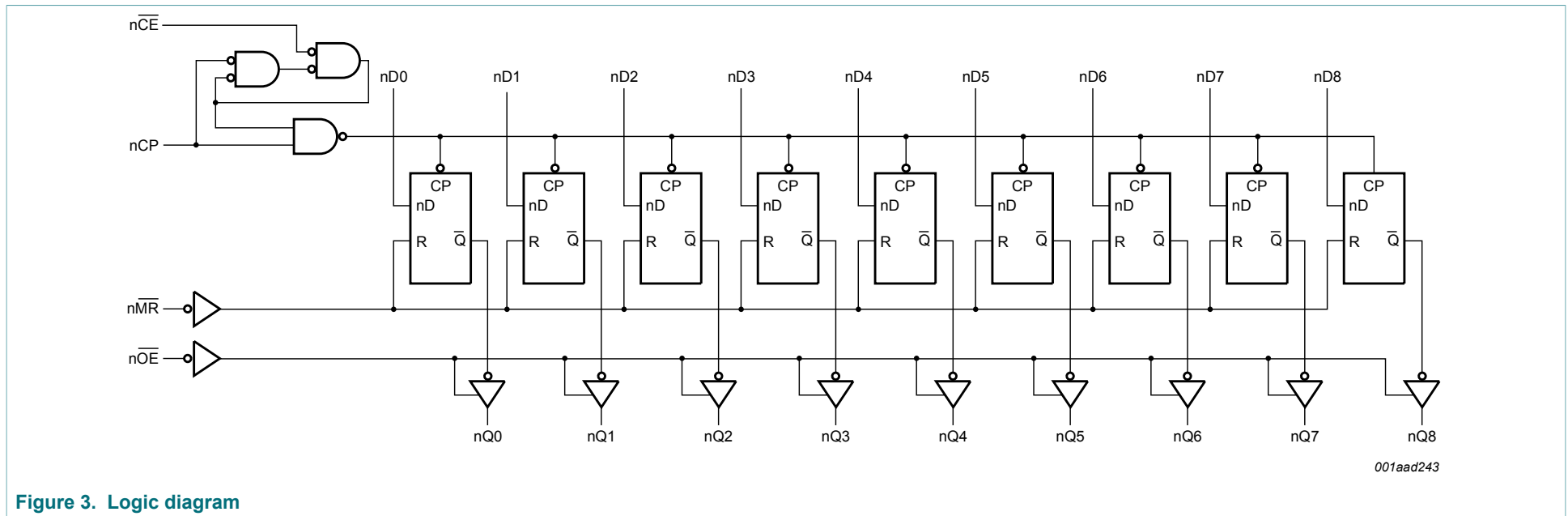
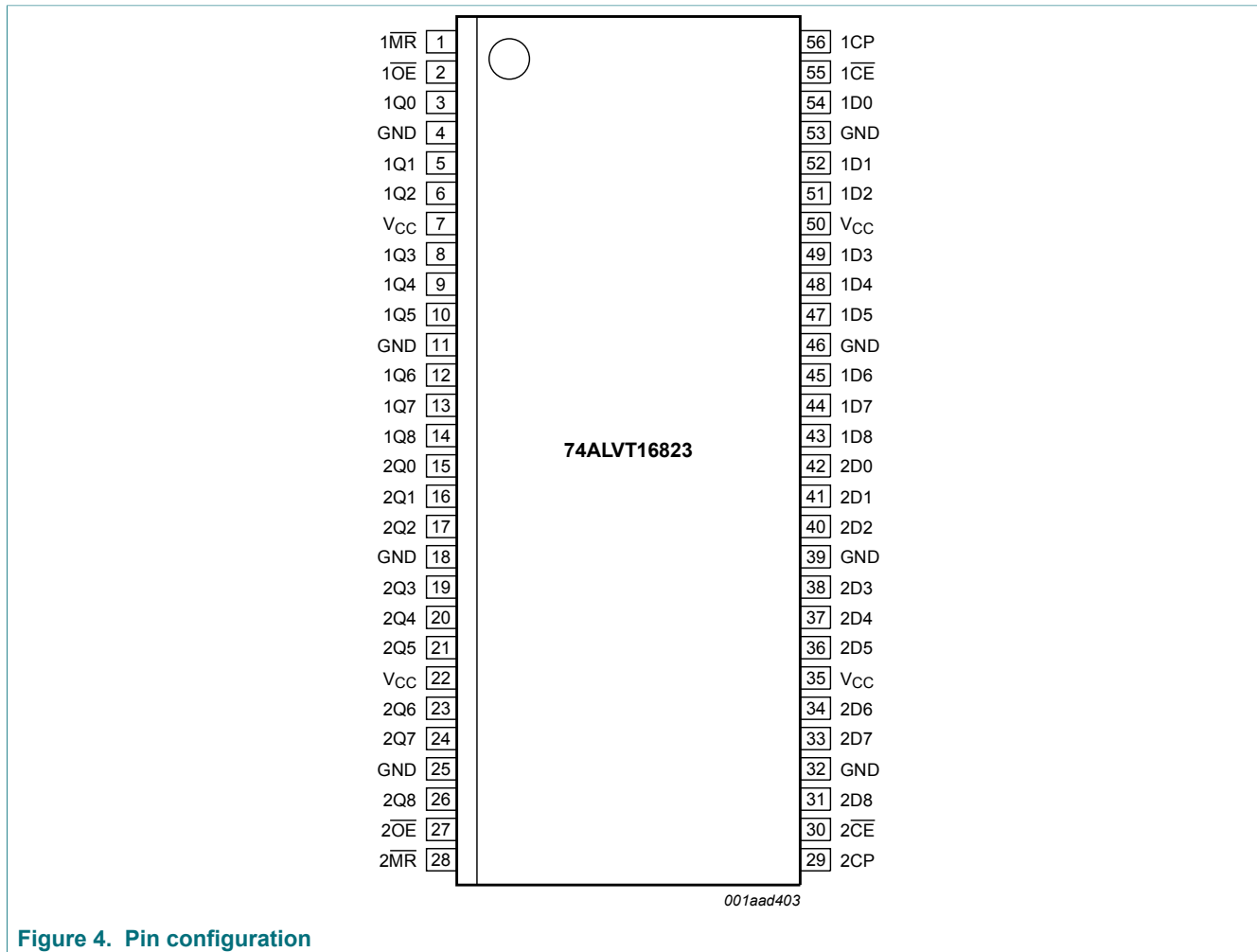


Figure 3. Logic diagram

5 Pinning information

5.1 Pinning



5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
1D0, 1D1, 1D2, 1D3, 1D4, 1D5, 1D6, 1D7, 1D8	54, 52, 51, 49, 48, 47, 45, 44, 43	data inputs
1Q0, 1Q1, 1Q2, 1Q3, 1Q4, 1Q5, 1Q6, 1Q7, 1Q8	3, 5, 6, 8, 9, 10, 12, 13, 14	data outputs
2D0, 2D1, 2D2, 2D3, 2D4, 2D5, 2D6, 2D7, 2D8	42, 41, 40, 38, 37, 36, 34, 33, 31	data inputs
2Q0, 2Q1, 2Q2, 2Q3, 2Q4, 2Q5, 2Q6, 2Q7, 2Q8	15, 16, 17, 19, 20, 21, 23, 24, 26	data outputs
1 $\overline{\text{MR}}$, 2 $\overline{\text{MR}}$	1, 28	master reset input (active-LOW)
1 $\overline{\text{OE}}$, 2 $\overline{\text{OE}}$	2, 27	output enable inputs (active LOW)
1CP, 2CP	56, 29	clock pulse inputs (active rising edge)
1 $\overline{\text{CE}}$, 2 $\overline{\text{CE}}$	55, 30	clock enable input (active-LOW)
GND	4, 11, 18, 25, 32, 39, 46, 53	ground (0 V)
V _{CC}	7, 22, 35, 50	supply voltage

6 Functional description

Table 3. Function table ^[1]

Operating mode	Input					Output
	n $\overline{\text{OE}}$	n $\overline{\text{MR}}$	n $\overline{\text{CE}}$	nCP	nDn	nQn
clear	L	L	X	X	X	L
load and read data	L	H	L	\uparrow	h	H
					l	L
hold	L	H	H	$\overline{\uparrow}$	X	NC
high-impedance	H	X	X	X	X	Z

- [1] H = HIGH voltage level;
 h = HIGH voltage level one set-up time prior to the LOW-to-HIGH clock transition;
 L = LOW voltage level;
 l = LOW voltage level one set-up time prior to the LOW-to-HIGH clock transition;
 NC = no change;
 X = don't care;
 Z = high-impedance OFF-state;
 \uparrow = LOW-to-HIGH clock transition;
 $\overline{\uparrow}$ = not a LOW-to-HIGH clock transition.

7 Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CC}	supply voltage		-0.5	+4.6	V
V_I	input voltage		[1] -0.5	+7.0	V
V_O	output voltage	output in OFF-state or HIGH-state	[1] -0.5	+7.0	V
I_{IK}	input clamping current	$V_I < 0$ V	-	-50	mA
I_{OK}	output clamping current	$V_O < 0$ V	-	-50	mA
I_O	output current	output in LOW-state	-	128	mA
		output in HIGH-state	-64	-	mA
T_{stg}	storage temperature		-65	+150	°C
T_j	junction temperature		[2] -	150	°C

[1] The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.

[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.

8 Recommended operating conditions

Table 5. Recommended operating conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC} = 2.5$ V						
V_{CC}	supply voltage		2.3	-	2.7	V
V_I	input voltage		0	-	5.5	V
I_{OH}	HIGH-level output current		-	-	-8	mA
I_{OL}	LOW-level output current	none	-	-	8	mA
		current duty cycle ≤ 50 %; $f \geq 1$ kHz	-	-	24	mA
$\Delta t/\Delta v$	input transition rise or fall rate	outputs enabled	-	-	10	ns/V
T_{amb}	ambient temperature	in free air	-40	-	+85	°C
$V_{CC} = 3.3$ V						
V_{CC}	supply voltage		3.0	-	3.6	V
V_I	input voltage		0	-	5.5	V
I_{OH}	HIGH-level output current		-	-	-32	mA
I_{OL}	LOW-level output current	none	-	-	32	mA
		current duty cycle ≤ 50 %; $f \geq 1$ kHz	-	-	64	mA
$\Delta t/\Delta v$	input transition rise or fall rate	outputs enabled	-	-	10	ns/V
T_{amb}	ambient temperature	in free air	-40	-	+85	°C

9 Static characteristics

Table 6. Static characteristics

At recommended operating conditions; $T_{amb} = -40\text{ }^{\circ}\text{C}$ to $+85\text{ }^{\circ}\text{C}$; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
$V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$						
V_{IK}	input clamping voltage	$V_{CC} = 2.3\text{ V}$; $I_{IK} = -18\text{ mA}$	-	-0.85	-1.2	V
V_{IH}	HIGH-level input voltage		1.7	-	-	V
V_{IL}	LOW-level input voltage		-	-	0.7	V
V_{OH}	HIGH-level output voltage	$V_{CC} = 2.3\text{ V}$ to 2.7 V ; $I_O = -100\text{ }\mu\text{A}$	$V_{CC} - 0.2$	V_{CC}	-	V
		$V_{CC} = 2.3\text{ V}$; $I_O = -8\text{ mA}$	1.8	2.5	-	V
V_{OL}	LOW-level output voltage	$V_{CC} = 2.3\text{ V}$; $I_O = 100\text{ }\mu\text{A}$	-	0.07	0.2	V
		$V_{CC} = 2.3\text{ V}$; $I_O = 24\text{ mA}$	-	0.3	0.5	V
		$V_{CC} = 2.3\text{ V}$; $I_O = 8\text{ mA}$	-	-	0.4	V
$V_{OL(pu)}$	power-up LOW-level output voltage	$V_{CC} = 2.7\text{ V}$; $I_O = 1\text{ mA}$; $V_I = V_{CC}$ or GND ^[2]	-	-	0.55	V
I_I	input leakage current	control pins				
		$V_{CC} = 2.7\text{ V}$; $V_I = V_{CC}$ or GND	-	0.1	± 1	μA
		$V_{CC} = 0\text{ V}$ to 2.7 V ; $V_I = 5.5\text{ V}$	-	0.1	10	μA
		I/O data pins ^[3]				
		$V_{CC} = 2.7\text{ V}$; $V_I = V_{CC}$	-	0.1	1	μA
	$V_{CC} = 2.7\text{ V}$; $V_I = 0\text{ V}$	-	+0.1	-5	μA	
I_{OFF}	power-off leakage current	$V_{CC} = 0\text{ V}$; V_I or $V_O = 0\text{ V}$ to 4.5 V	-	+0.1	± 100	μA
I_{BHL}	bus hold LOW current	data inputs; $V_{CC} = 2.3\text{ V}$; $V_I = 0.7\text{ V}$ ^[4]	-	100	-	μA
I_{BHH}	bus hold HIGH current	data inputs; $V_{CC} = 2.3\text{ V}$; $V_I = 1.7\text{ V}$ ^[4]	-	-70	-	μA
I_{EX}	external current	output HIGH-state when $V_O > V_{CC}$; $V_O = 5.5\text{ V}$; $V_{CC} = 2.3\text{ V}$	-	10	125	μA
$I_{O(pu/pd)}$	power-up/power-down output current	$V_{CC} \leq 1.2\text{ V}$; $V_O = 0.5\text{ V}$ to V_{CC} ; $V_I = \text{GND}$ or V_{CC} ^[5]	-	1	± 100	μA
I_{OZ}	OFF-state output current	$V_{CC} = 2.7\text{ V}$; $V_I = V_{IL}$ or V_{IH}				
		output HIGH state; $V_O = 2.3\text{ V}$	-	0.5	5	μA
		output LOW-state; $V_O = 0.5\text{ V}$	-	+0.5	-5	μA
I_{CC}	supply current	$V_{CC} = 2.7\text{ V}$; $V_I = \text{GND}$ or V_{CC} ; $I_O = 0\text{ A}$				
		outputs HIGH-state	-	0.04	0.1	mA
		outputs LOW-state	-	2.7	4.5	mA
		outputs disabled ^[6]	-	0.04	0.1	mA
ΔI_{CC}	additional supply current	per input pin; $V_{CC} = 2.3\text{ V}$ to 2.7 V ; one input at $V_{CC} - 0.6\text{ V}$, other inputs at V_{CC} or GND ^[7]	-	0.04	0.4	mA
C_I	input capacitance	$V_I = 0\text{ V}$ or V_{CC}	-	3	-	pF
C_O	output capacitance	$V_{IO} = 0\text{ V}$ or 3.0 V	-	9	-	pF

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
V_{CC} = 3.3 V ± 0.3 V						
V _{IK}	input clamping voltage	V _{CC} = 3.0 V; I _{IK} = -18 mA	-	-0.85	-1.2	V
V _{IH}	HIGH-level input voltage		2.0	-	-	V
V _{IL}	LOW-level input voltage		-	-	0.8	V
V _{OH}	HIGH-level output voltage	V _{CC} = 3.0 V to 3.6 V; I _O = -100 µA	V _{CC} - 0.2	V _{CC}	-	V
		V _{CC} = 3.0 V; I _O = -32 mA	2.0	2.3	-	V
V _{OL}	LOW-level output voltage	V _{CC} = 3.0 V; I _O = 100 µA	-	0.07	0.2	V
		V _{CC} = 3.0 V; I _O = 16 mA	-	0.25	0.4	V
		V _{CC} = 3.0 V; I _O = 32 mA	-	0.3	0.5	V
		V _{CC} = 3.0 V; I _O = 64 mA	-	0.4	0.55	V
V _{OL(pu)}	power-up LOW-level output voltage	V _{CC} = 3.6 V; I _O = 1 mA; V _I = V _{CC} or GND ^[2]	-	-	0.55	V
I _I	input leakage current	control pins				
		V _{CC} = 3.6 V; V _I = V _{CC} or GND	-	0.1	±1	µA
		V _{CC} = 0 V or 3.6 V; V _I = 5.5 V	-	0.1	10	µA
		I/O data pins ^[3]				
		V _{CC} = 3.6 V; V _I = V _{CC}	-	0.5	1	µA
		V _{CC} = 3.6 V; V _I = 0 V	-	+0.1	-5	µA
I _{OFF}	power-off leakage current	V _{CC} = 0 V; V _I or V _O = 0 V to 4.5 V	-	0.1	±100	µA
I _{BHL}	bus hold LOW current	data inputs; V _{CC} = 3 V; V _I = 0.8 V	75	130	-	µA
I _{BHH}	bus hold HIGH current	data inputs; V _{CC} = 3 V; V _I = 2.0 V	-75	-140	-	µA
I _{BHLO}	bus hold LOW overdrive current	data inputs; V _{CC} = 3.6 V; V _I = 0 V to 3.6 V ^[8]	500	-	-	µA
I _{BHHO}	bus hold HIGH overdrive current	data inputs; V _{CC} = 3.6 V; V _I = 0 V to 3.6 V ^[8]	-500	-	-	µA
I _{EX}	external current	output HIGH-state when V _O > V _{CC} ; V _O = 5.5 V; V _{CC} = 3.0 V	-	10	125	µA
I _{O(pu pd)}	power-up/power-down output current	V _{CC} ≤ 1.2 V; V _O = 0.5 V to V _{CC} ; V _I = GND or V _{CC} ^[9]	-	1	±100	µA
I _{OZ}	OFF-state output current	V _{CC} = 3.6 V; V _I = V _{IL} or V _{IH}				
		output HIGH state; V _O = 3.0 V	-	0.5	5	µA
		output LOW-state; V _O = 0.5 V	-	+0.5	-5	µA
I _{CC}	supply current	V _{CC} = 3.6 V; V _I = GND or V _{CC} ; I _O = 0 A				
		outputs HIGH-state	-	0.06	0.1	mA
		outputs LOW-state	-	3.9	5.5	mA
		outputs disabled ^[6]	-	0.06	0.1	mA
ΔI _{CC}	additional supply current	per input pin; V _{CC} = 3 V to 3.6 V; one input at V _{CC} - 0.6 V, other inputs at V _{CC} or GND ^[7]	-	0.04	0.4	mA

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
C _I	input capacitance	V _I = 0 V or V _{CC}	-	3	-	pF
C _O	output capacitance	V _{I/O} = 0 V or 3.0 V	-	9	-	pF

[1] All typical values for V_{CC} = 2.5 V ± 0.2 V are measured at V_{CC} = 2.5 V and T_{amb} = 25 °C.

All typical values for V_{CC} = 3.3 V ± 0.3 V are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.

[2] For valid test results, data must not be loaded into the flip-flops after applying power.

[3] Unused pins at V_{CC} or GND.

[4] Not guaranteed.

[5] This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 ms. From V_{CC} = 1.2 V to V_{CC} = 2.5 V ± 0.2 V a transition time of 100 μs is permitted. This parameter is valid for T_{amb} = 25 °C only.

[6] I_{CC} is measured with outputs pulled up to V_{CC} or pulled down to ground.

[7] This is the increase in supply current for each input at the specified voltage level other than V_{CC} or GND.

[8] This is the bus hold overdrive current required to force the input to the opposite logic state.

[9] This parameter is valid for any V_{CC} between 0 V and 1.2 V with a transition time of up to 10 ms. From V_{CC} = 1.2 V to V_{CC} = 3.3 V ± 0.3 V a transition time of 100 μs is permitted. This parameter is valid for T_{amb} = 25 °C only.

10 Dynamic characteristics

Table 7. Dynamic characteristics

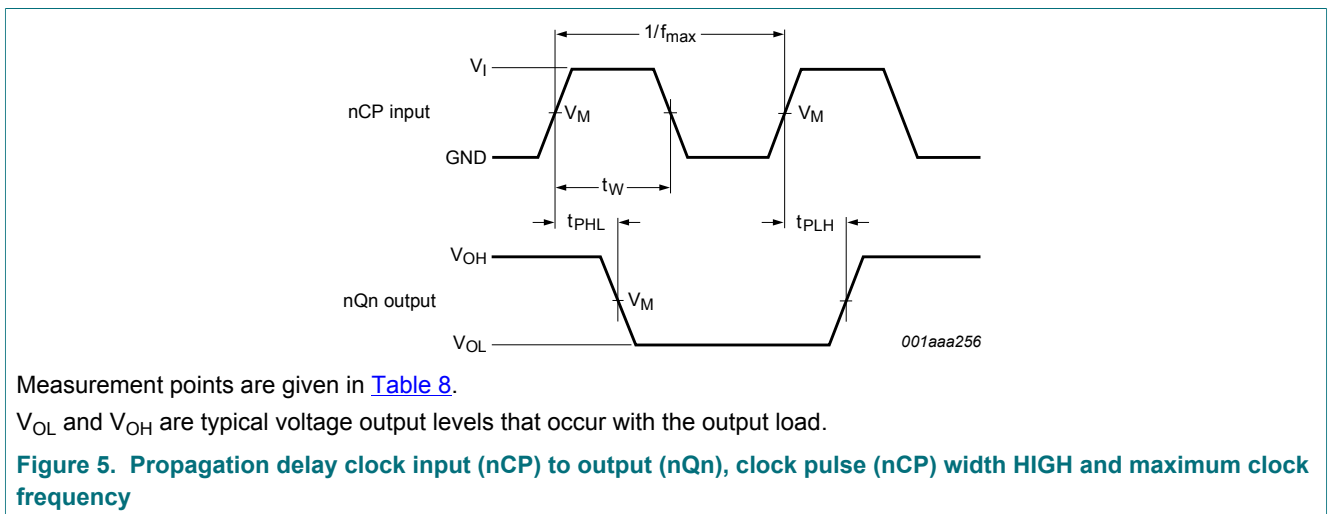
Voltages are referenced to GND (ground = 0 V); T_{amb} = -40 °C to +85 °C; for test circuit see [Figure 9](#).

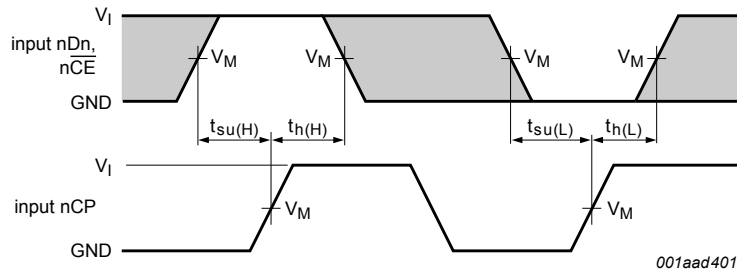
Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
V_{CC} = 2.5 V ± 0.2 V						
t _{PLH}	LOW to HIGH propagation delay	nCP to nQn; see Figure 5	1.5	2.9	4.5	ns
t _{PHL}	HIGH-to-LOW propagation delay	nCP to nQn; see Figure 5	1.4	2.7	4.2	ns
		nMR to nQn; see Figure 7	1.5	2.7	4.2	ns
t _{PZH}	OFF-state to HIGH propagation delay	nOE to nQn; see Figure 8	2.1	3.4	5.0	ns
t _{PZL}	OFF-state to LOW propagation delay	nOE to nQn; see Figure 8	1.8	3.0	4.7	ns
t _{PHZ}	HIGH to OFF-state propagation delay	nOE to nQn; see Figure 8	1.7	3.0	4.3	ns
t _{PLZ}	LOW to OFF-state propagation delay	nOE to nQn; see Figure 8	1.4	2.3	3.3	ns
t _{su(H)}	set-up time HIGH	nDn to nCP; see Figure 6	1.0	0.5	-	ns
		nCE to nCP; see Figure 6	1.0	0.2	-	ns
t _{su(L)}	set-up time LOW	nDn to nCP; see Figure 6	1.8	1.3	-	ns
		nCE to nCP; see Figure 6	0.5	-0.1	-	ns
t _{h(H)}	hold time HIGH	nDn to nCP; see Figure 6	0.1	-1.4	-	ns
		nCE to nCP; see Figure 6	1.0	0.2	-	ns
t _{h(L)}	hold time LOW	nDn to nCP; see Figure 6	0.1	-0.5	-	ns
		nCE to nCP; see Figure 6	1.0	-0.1	-	ns
t _{WH}	pulse width HIGH	nCP; see Figure 5	2.0	0.8	-	ns
t _{WL}	pulse width LOW	nCP	3.0	2.1	-	ns
		nMR; see Figure 7	2.0	0.8	-	ns
t _{rec}	recovery time	nMR to nCP; see Figure 7	2.0	1.3	-	ns
f _{max}	maximum frequency	CP; see Figure 5	150	-	-	MHz

Symbol	Parameter	Conditions	Min	Typ ^[1]	Max	Unit
V_{CC} = 3.3 V ± 0.3 V						
t _{PLH}	LOW to HIGH propagation delay	nCP to nQn; see Figure 5	1.0	2.3	3.1	ns
t _{PHL}	HIGH-to-LOW propagation delay	nCP to nQn; see Figure 5	1.0	2.1	2.9	ns
		nMR to nQn; see Figure 7	1.0	2.3	2.9	ns
t _{PZH}	OFF-state to HIGH propagation delay	nOE to nQn; see Figure 8	1.7	2.7	4.0	ns
t _{PZL}	OFF-state to LOW propagation delay	nOE to nQn; see Figure 8	1.4	2.3	3.5	ns
t _{PHZ}	HIGH to OFF-state propagation delay	nOE to nQn; see Figure 8	2.2	3.1	4.0	ns
t _{PLZ}	LOW to OFF-state propagation delay	nOE to nQn; see Figure 8	1.8	2.6	3.5	ns
t _{su(H)}	set-up time HIGH	nDn to nCP; see Figure 6	1.0	0.5	-	ns
		nCE to nCP; see Figure 6	1.0	0.1	-	ns
t _{su(L)}	set-up time LOW	nDn to nCP; see Figure 6	1.6	1.1	-	ns
		nCE to nCP; see Figure 6	0.5	-0.5	-	ns
t _{h(H)}	hold time HIGH	nDn to nCP; see Figure 6	0.1	-0.7	-	ns
		nCE to nCP; see Figure 6	1.0	0.5	-	ns
t _{h(L)}	hold time LOW	nDn to nCP; see Figure 6	0.1	-0.5	-	ns
		nCE to nCP; see Figure 6	1.0	-0.1	-	ns
t _{WH}	pulse width HIGH	nCP; see Figure 5	1.5	0.7	-	ns
t _{WL}	pulse width LOW	nCP	2.5	1.4	-	ns
		nMR; see Figure 7	2.0	1.5	-	ns
t _{rec}	recovery time	nMR to nCP; see Figure 7	2.0	1.1	-	ns
f _{max}	maximum frequency	CP; see Figure 5	250	-	-	MHz

[1] All typical values for V_{CC} = 2.5 V ± 0.2 V are measured at V_{CC} = 2.5 V and T_{amb} = 25 °C.
 All typical values for V_{CC} = 3.3 V ± 0.3 V are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.

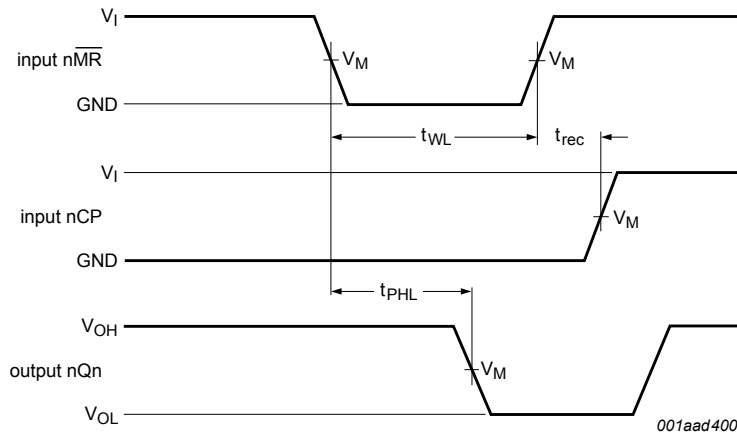
10.1 Waveforms and test circuit





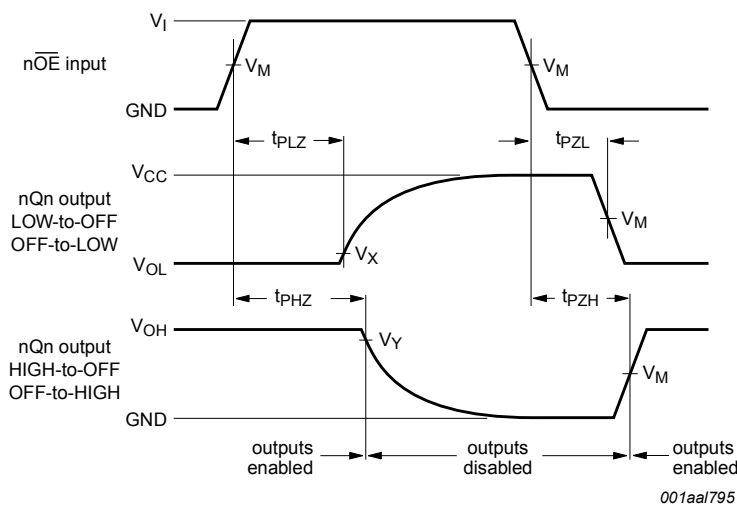
Measurement points are given in [Table 8](#).
The shaded areas indicate when the input is permitted to change for predictable output performance.

Figure 6. Data set-up and hold times



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Figure 7. Master reset pulse width, master reset to output delay and master reset to clock recovery time



Measurement points are given in [Table 8](#).
 V_{OL} and V_{OH} are typical voltage output levels that occur with the output load.

Figure 8. OFF-state to HIGH and LOW propagation delays and LOW and HIGH to OFF-state propagation delays

Table 8. Measurement points

V _{CC}	Input	Output		
	V _M	V _M	V _X	V _Y
≤ 2.7 V	0.5 x V _{CC}	0.5 x V _{CC}	V _{OL} + 0.15 V	V _{OH} - 0.15 V
≥ 3.0 V	1.5 V	1.5 V	V _{OL} + 0.3 V	V _{OH} - 0.3 V

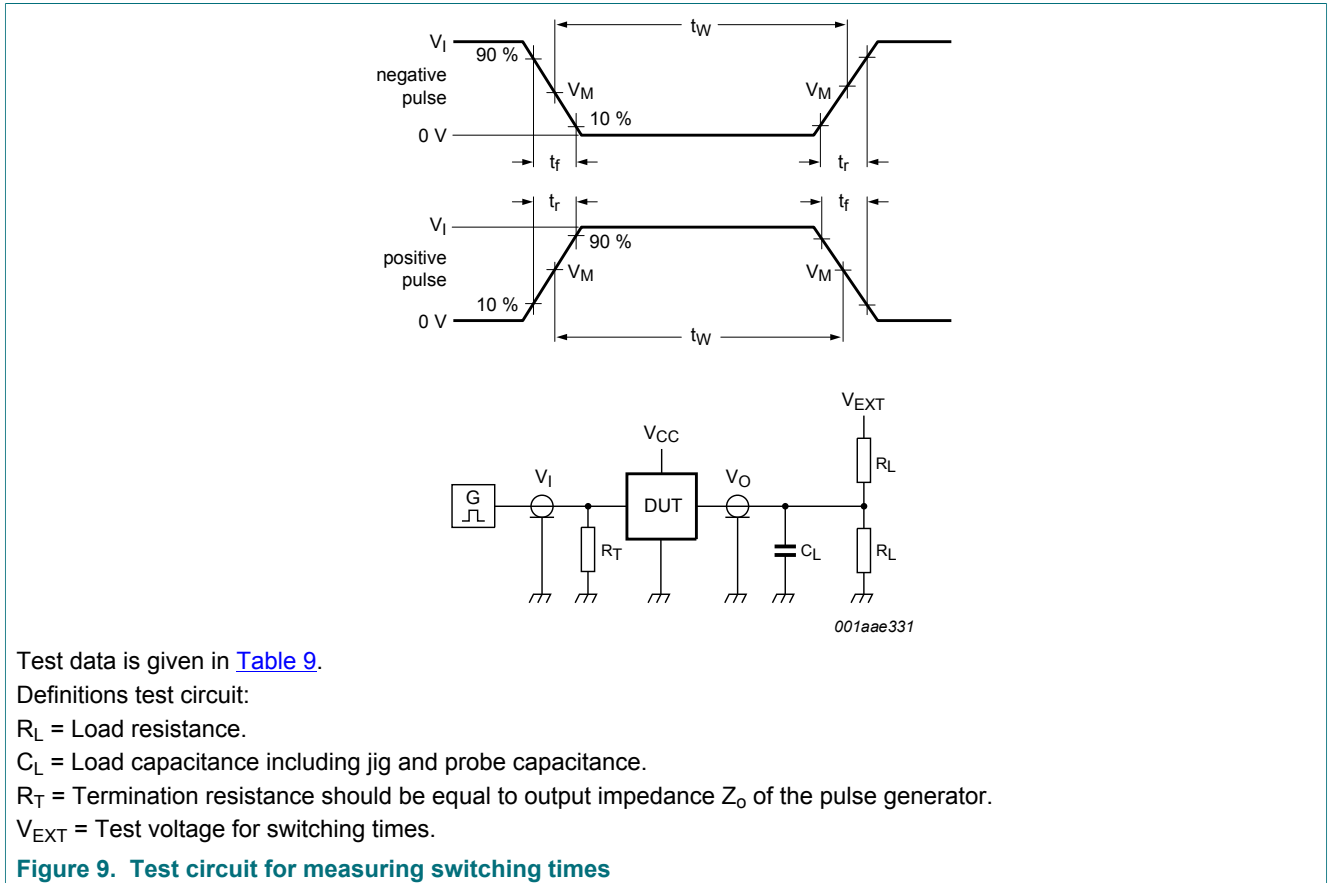


Table 9. Test data

Input			Load			V _{EXT}		
V _I	f _i	t _W	t _r , t _f	C _L	R _L	t _{PHZ} , t _{PZH}	t _{PLZ} , t _{PZL}	t _{PLH} , t _{PHL}
3.0 V or V _{CC} whichever is less	≤ 10 MHz	500 ns	≤ 2.5 ns	50 pF	500 Ω	GND	6 V or V _{CC} x 2	open

11 Package outline

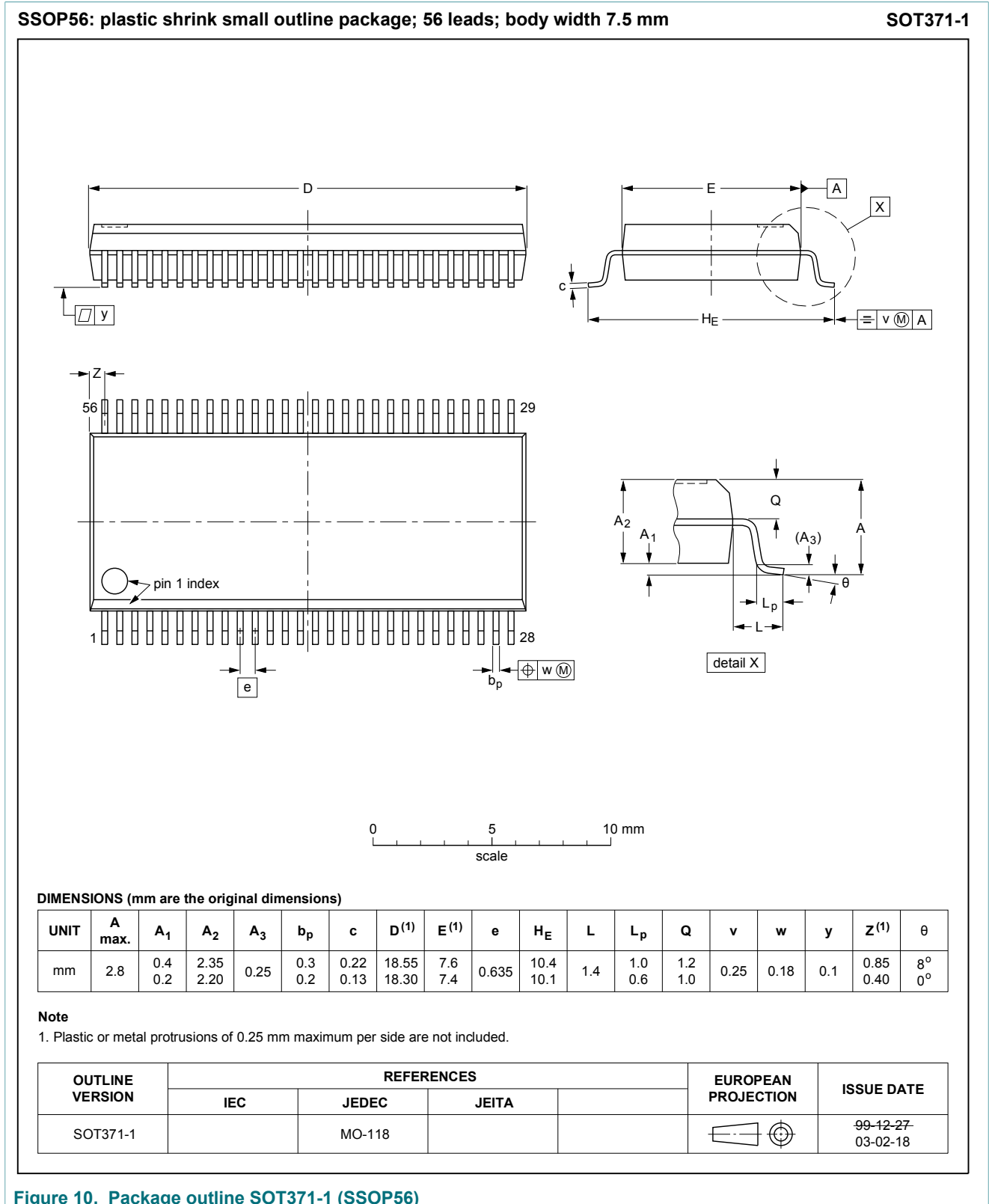
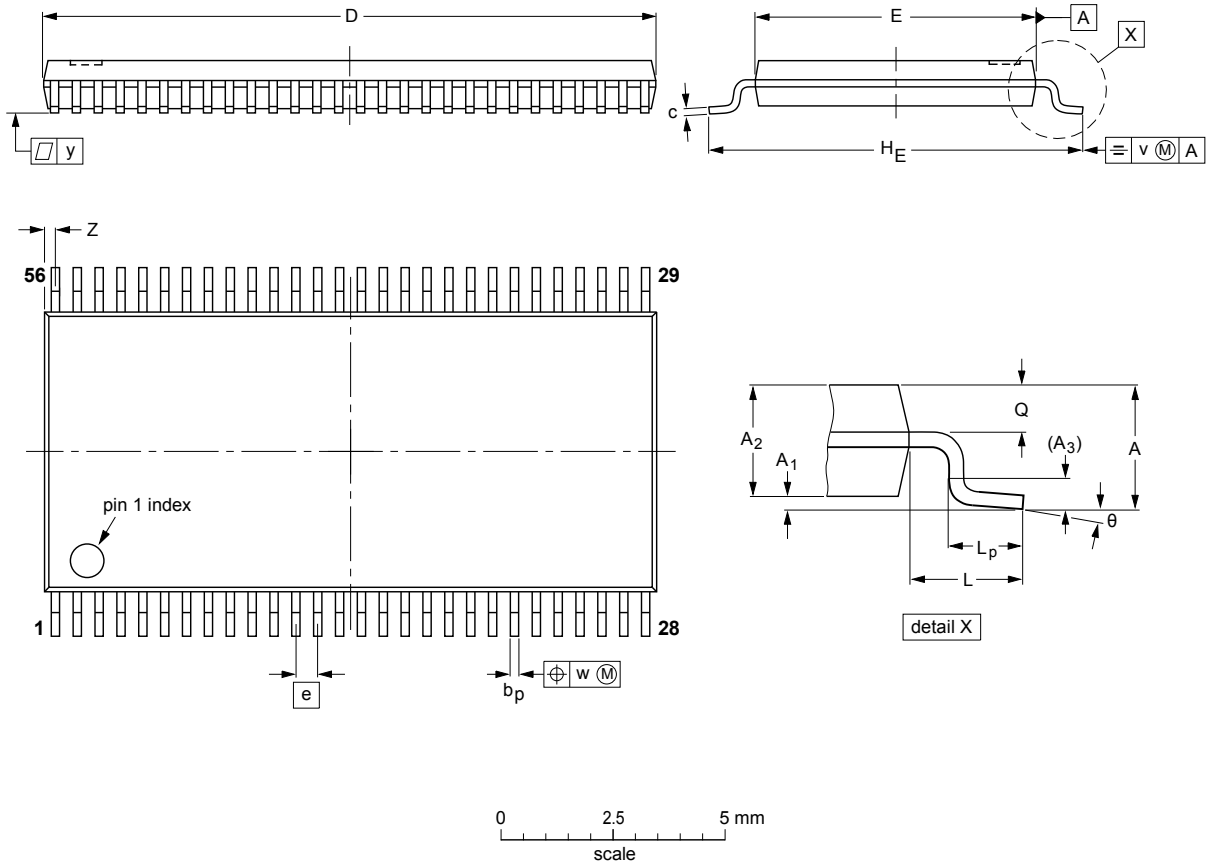


Figure 10. Package outline SOT371-1 (SSOP56)

TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1 mm

SOT364-1



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	14.1 13.9	6.2 6.0	0.5	8.3 7.9	1	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.5 0.1	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT364-1		MO-153				-99-12-27 03-02-19

Figure 11. Package outline SOT364-1 (TSSOP56)

12 Abbreviations

Table 10. Abbreviations

Acronym	Description
DUT	Device Under Test
ESD	ElectroStatic Discharge
MIL	Military
MM	Machine Model
MOS	Metal-Oxide Semiconductor

13 Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74ALVT16823 v.5	20180122	Product data sheet	-	74ALVT16823 v.4
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia. Legal texts have been adapted to the new company name where appropriate. 			
74ALVT16823 v.4	20050802	Product data sheet	-	74ALVT16823 v.3
Modifications:	<ul style="list-style-type: none"> The format of this data sheet has been redesigned to comply with the new presentation and information standard of Philips Semiconductors. Section 2: modified 'Jedec Std 17' into 'JESD78' Section 10: changed propagation delays. 			
74ALVT16823 v.3	19980612	Product specification	-	74ALVT16823 v.2
74ALVT16823 v.2	19980612	Product specification	-	74ALVT16823 v.1
74ALVT16823 v.1	19980303	Product specification	-	-

14 Legal information

14.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nexperia.com>.

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Date of release: 22 January 2018
Document identifier: 74ALVT16823

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